



## Material Content Data Sheet



<b>Sales Product Name</b>		TLE7273-2G V50		<b>Issued</b>		4. October 2018		
<b>MA#</b>		MA000970184						
<b>Package</b>		PG-DSO-14-30		<b>Weight*</b>		143.09 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.362	1.65	1.65	16506	16506
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		105	
	non noble metal	zinc	7440-66-6	0.060	0.04		422	
	non noble metal	iron	7439-89-6	1.207	0.84		8435	
wire	non noble metal	copper	7440-50-8	49.007	34.25	35.14	342491	351453
	noble metal	gold	7440-57-5	0.302	0.21	0.21	2113	2113
	encapsulation	organic material	carbon black	1333-86-4	0.173	0.12		1211
plastics		epoxy resin	-	7.969	5.57		55693	
	inorganic material	silicondioxide	60676-86-0	78.479	54.85	60.54	548459	605363
leadfinish	non noble metal	tin	7440-31-5	1.226	0.86	0.86	8569	8569
plating	noble metal	silver	7440-22-4	1.030	0.72	0.72	7197	7197
glue	plastics	acrylic resin	-	0.277	0.19		1936	
	noble metal	silver	7440-22-4	0.982	0.69	0.88	6863	8799
*deviation	< 10%					Sum in total:	100.00	1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com